PACKAGE INFORMATION

The flip-chip die is housed in a custom 16-pin QFN package shown in Fig. 1. The back side of the die is exposed at the top of the package to provide the heat dissipation path. An external heat sink can be attached to the exposed top.

The InfoCube part's identification label is IFC211. The Adsnatec part's identification label is ASNT5143-ALD. The first 8 characters of the name before the dash identify the bare die including general circuit family, fabrication technology, specific circuit type, and part version while the 3 characters after the dash represent the package's manufacturer, type, and pin out count.

This device complies with the Restriction of Hazardous Substances (RoHS) per 2011/65/EU for all ten substances.

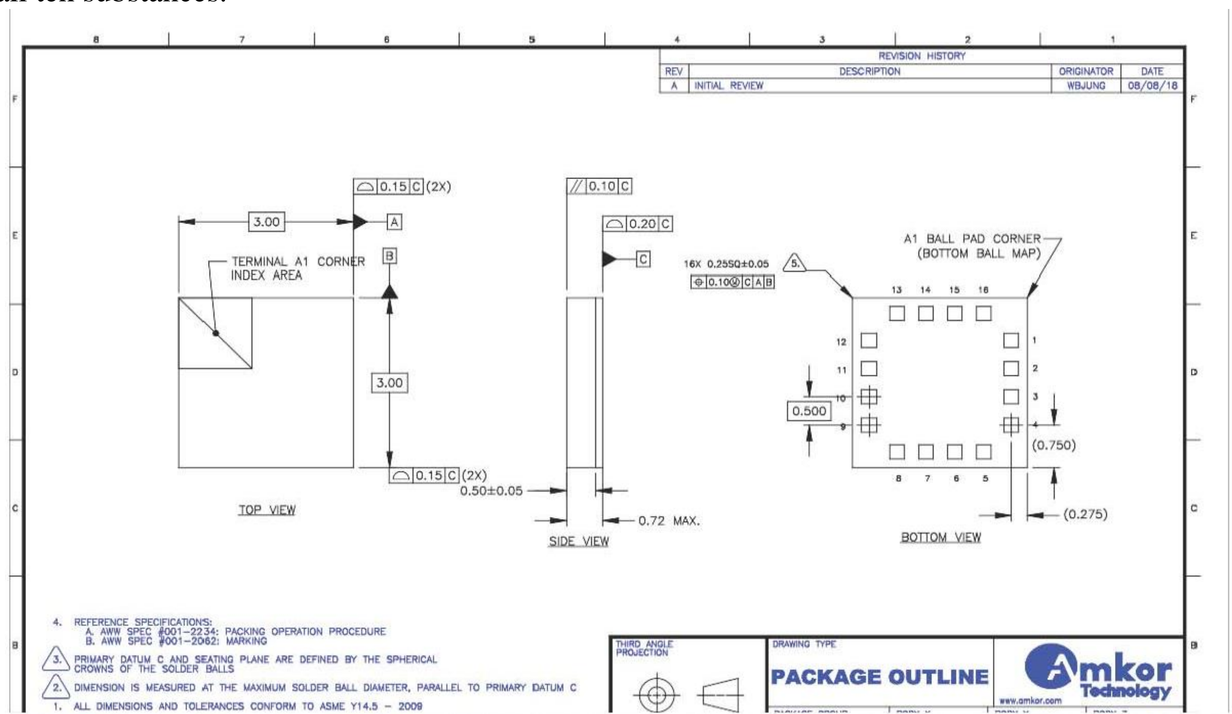

Fig. 1. LGA 16-Pin Package Drawing (All Dimensions in mm)